FIG.1

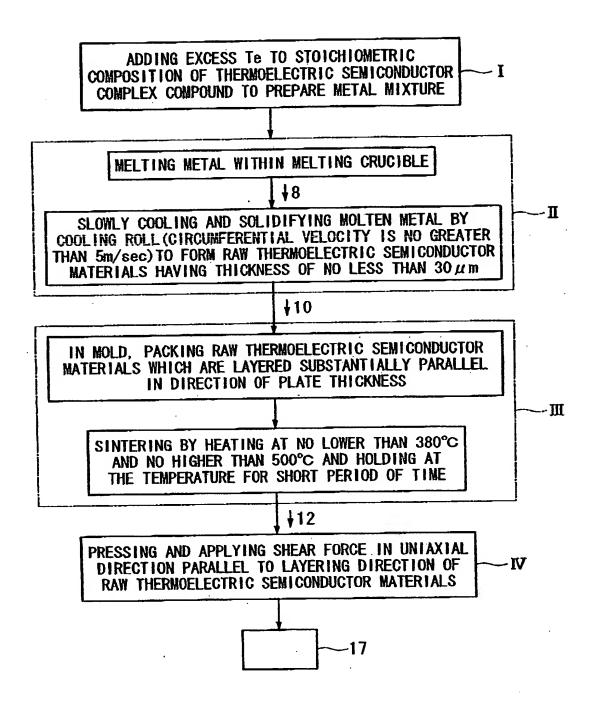


FIG. 2

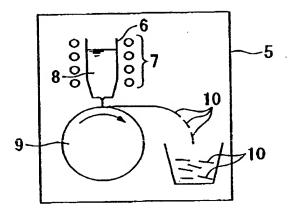


FIG. 3

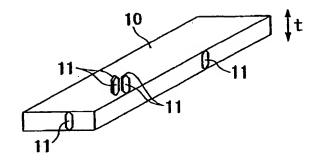


FIG. 4

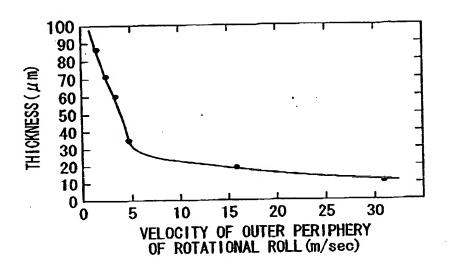


FIG. 5

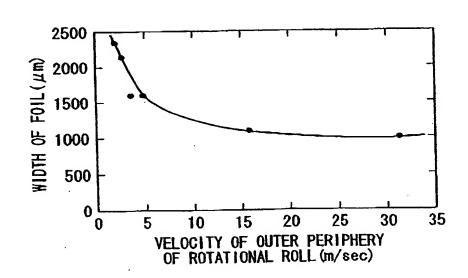


FIG. 6A

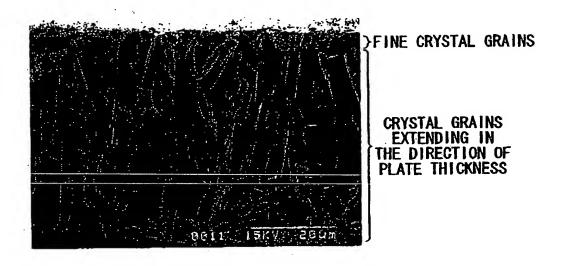
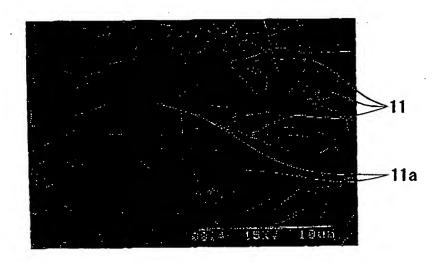
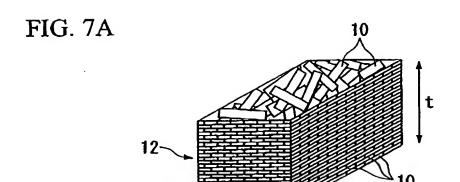
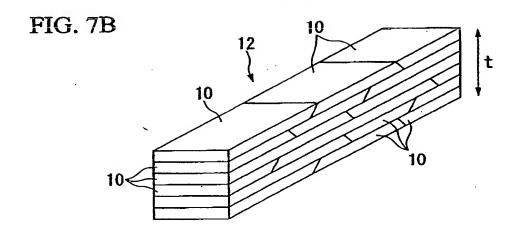
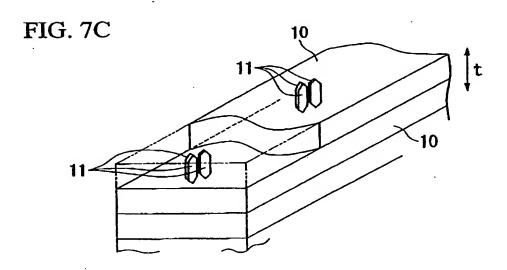


FIG. 6B









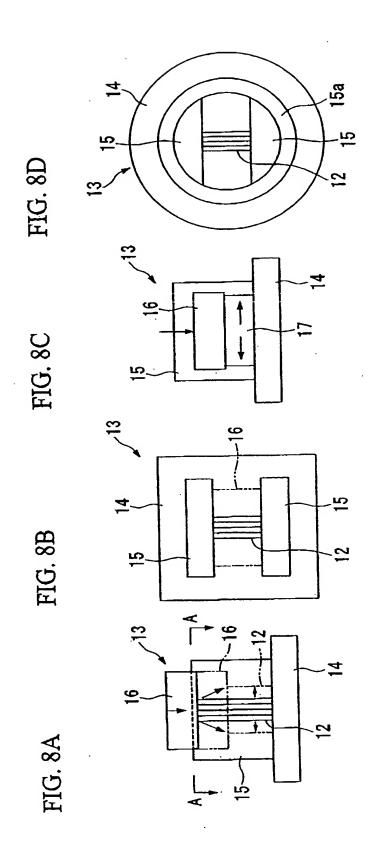


FIG. 9A

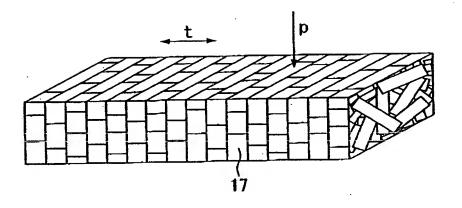


FIG. 9B

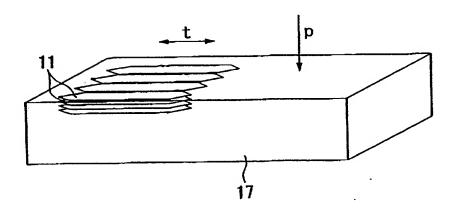


FIG. 10

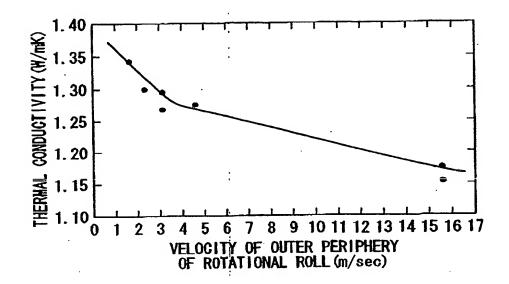


FIG. 11

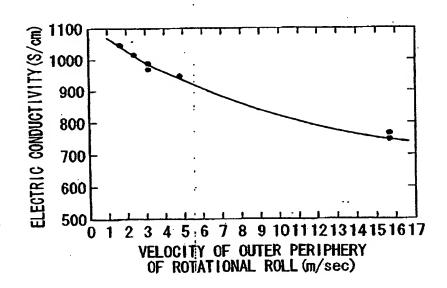


FIG. 12

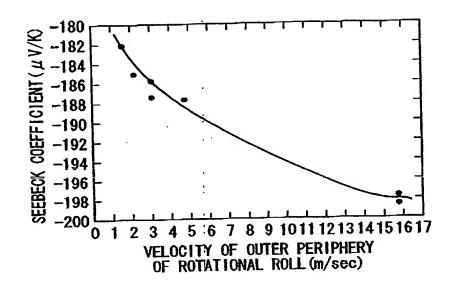


FIG. 13

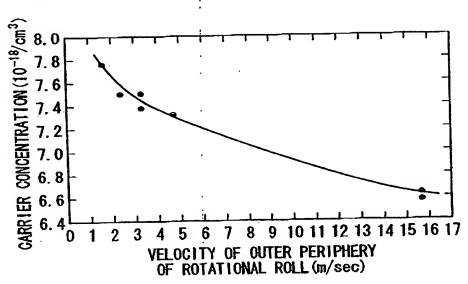


FIG. 14

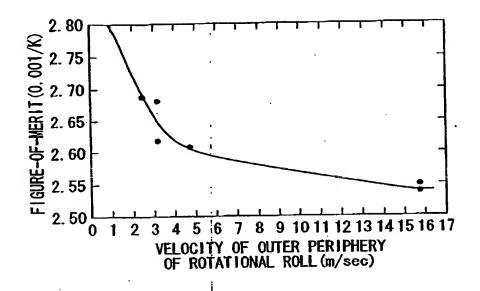


FIG. 15

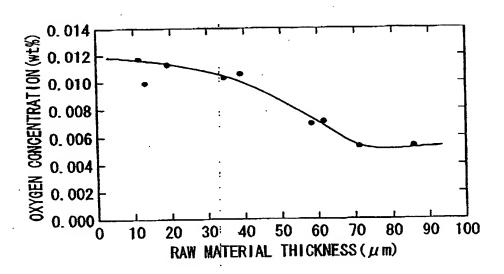


FIG. 16

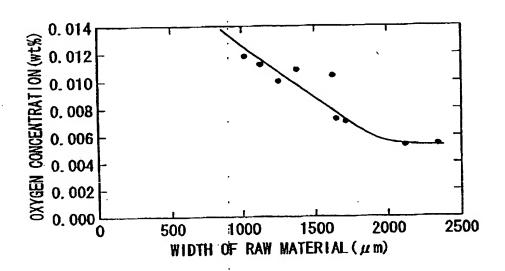


FIG. 17

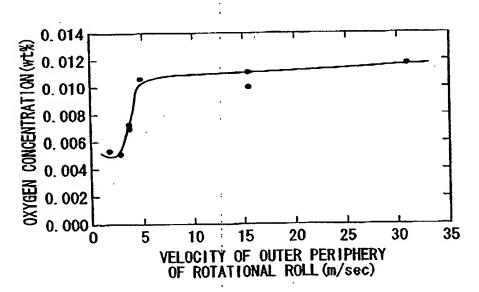
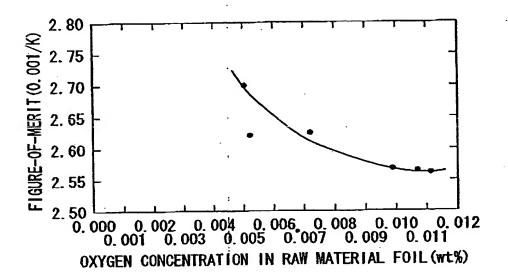
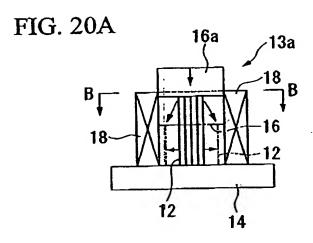


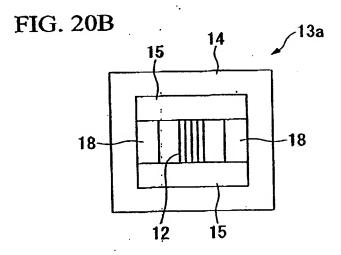
FIG. 18

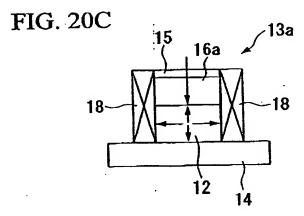


ADDING EXCESS TO TO STOICHIOMETRIC COMPOSITION OF THERMOELECTRIC SEMICONDUCTOR – I COMPLEX COMPOUND TO PREPARE METAL MIXTURE MELTING METAL WITHIN MELTING CRUCIBLE **†8** SLOWLY COOLING AND SOLIDIFYING MOLTEN METAL BY COOLING ROLL (CIRCUMFERENTIAL VELOCITY IS NO GREATER THAN 5m/sec) TO FORM RAW THERMOELECTRIC SEMICONDUCTOR MATERIALS HAVING THICKNESS OF NO LESS THAN 30 μ m <u> — П</u> 110 IN MOLD, PACKING RAW THERMOELECTRIC SEMICONDUCTOR MATERIALS WHICH ARE LAYERED SUBSTANTIALLY PARALLEL PACKING RAW THERMOELECTRIC SENICONDUCTOR IN DIRECTION OF PLATE THICKNESS **~**Ⅲ SINTERING BY HEATING AT NO LOWER THAN 380°C AND NO HIGHER THAN 500°C AND HOLDING AT THE TEMPERATURE FOR SHORT PERIOD OF TIME 112 PRESSING AND APPLYING SHEAR FORCE IN UNIAXIAL DIRECTION PARALLEL TO LAYERING DIRECTION OF -IV-1 RAW THERMOELECTRIC ISENICONDUCTOR MATERIALS PRESSING BY OMNIDIRECTIONAL HYDROSTATIC PRESSURE -W-2 PRESSING AND APPLYING SHEAR FORCE IN UNIAXIAL DIRECTION PARALLEL TO LAYERING DIRECTION OF RAW THERMOELECTRIC SEMICONDUCTOR MATERIALS ·IV – 1 -- IV 117 MAINTAINING THERMOELECTRIC SEMICONDUCTOR MATERIAL AT PREDETERMINED TEMPERATURE FOR PREDETERMINED PERIOD OF TIME AND REMOVING RESIDUAL STRESS STRAIN MAINTAINING THERMOELECTRIC SEMICONDUCTOR MATERIAL AT PREDETERMINED TEMPERATURE FOR PREDETERMINED PERIOD OF TIME, TO CHANGE DEFECTS CONCENTRATION AND CONTROL ELECTRIC CONDUCTIVITY AND SEEBECK COEFFICIENT -VI -17

60. 52.205**3**







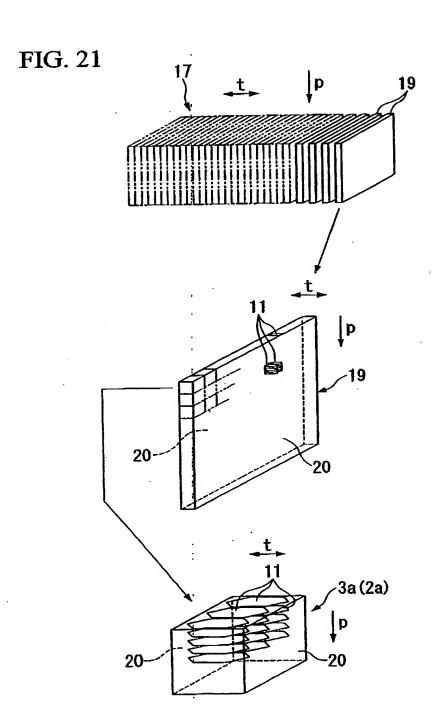


FIG. 22

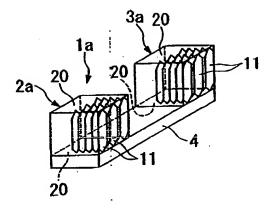


FIG. 23

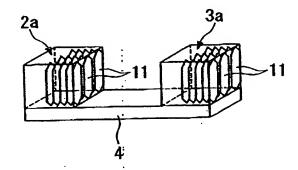


FIG. 24A

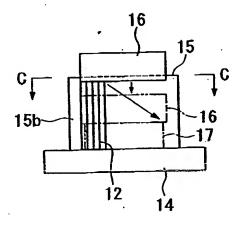


FIG. 24B

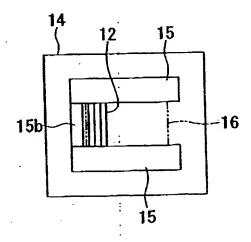


FIG. 25A

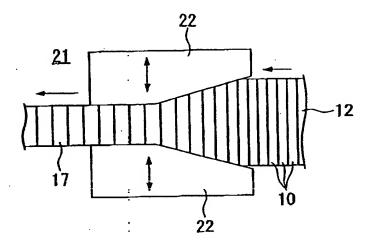


FIG. 25B

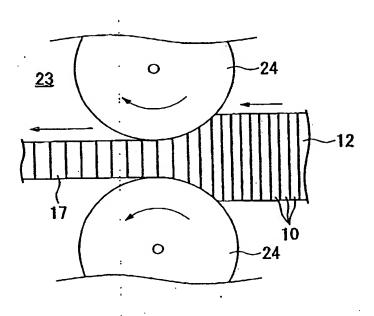


FIG. 26

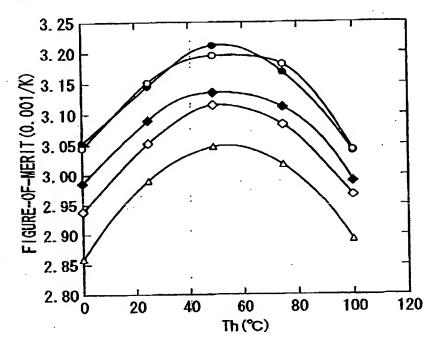


FIG. 27

